

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA189ID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA189
OPA189ID.Z	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA189
OPA189IDBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1CTV
OPA189IDBVR.Z	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1CTV
OPA189IDBVT	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1CTV
OPA189IDBVT.Z	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1CTV
OPA189IDBVTG4.Z	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1CTV
OPA189IDGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CS6
OPA189IDGKR.Z	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CS6
OPA189IDGKT	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CS6
OPA189IDGKT.Z	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CS6
OPA189IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA189
OPA189IDR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA189
OPA189IDRG4.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA189
OPA2189ID	Active	Production	SOIC (D) 8	75 TUBE	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OP2189
OPA2189ID.Z	Active	Production	SOIC (D) 8	75 TUBE	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OP2189
OPA2189IDGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1VQQ
OPA2189IDGKR.Z	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1VQQ
OPA2189IDGKT	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1VQQ
OPA2189IDGKT.Z	Active	Production	VSSOP (DGK) 8	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1VQQ
OPA2189IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OP2189
OPA2189IDR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OP2189
OPA4189IDR	Active	Production	SOIC (D) 14	3000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IDR.Z	Active	Production	SOIC (D) 14	3000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IDT	Active	Production	SOIC (D) 14	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IDT.Z	Active	Production	SOIC (D) 14	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IPWR	Active	Production	TSSOP (PW) 14	3000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IPWR.Z	Active	Production	TSSOP (PW) 14	3000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189
OPA4189IPWT	Active	Production	TSSOP (PW) 14	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA4189IPWT.Z	Active	Production	TSSOP (PW) 14	250 SMALL T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	OPA4189

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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